

PW3439K

20V N-Channel + P-Channel MOSFET

-0.66A -20V; $R_{DS(ON)typ}=450m\Omega$ @-4.5V,
 $R_{DS(ON)typ}=650m\Omega$ @-2.5V, $R_{DS(ON)typ}=950m\Omega$ @-1.8V.
0.75A 20V; $R_{DS(ON)typ}=190m\Omega$ @4.5V,
 $R_{DS(ON)typ}=260m\Omega$ @2.5V, $R_{DS(ON)typ}=390m\Omega$ @1.8V.

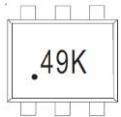
FEATURE

- Surface Mount Package
- Low $R_{DS(on)}$
- Operated at Low Logic Level Gate Drive
- ESD Protected Gate

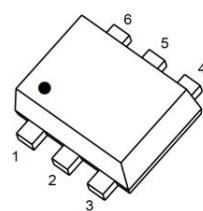
Application

- Load/ Power Switching
- Interfacing Switching
- Battery Management for Ultra Small Portable Electronics
- Logic Level Shift

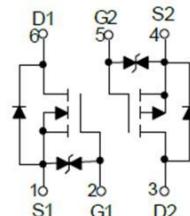
MARKING:



SOT-563



Schematic diagram



ABSOLUTE MAXIMUM RATINGS (T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
P-MOSFET			
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	V _{GS}	±12	V
Continuous Drain Current ⁽¹⁾	I _D	-0.66	A
Pulsed Drain Current(tp=10μs)	I _{DM}	-1.2	A
N-MOSFET			
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±12	V
Continuous Drain Current ⁽¹⁾	I _D	0.75	A
Pulsed Drain Current(tp=10μs)	I _{DM}	1.8	A
Temperature and Thermal Resistance			
Thermal Resistance from Junction to Ambient ⁽¹⁾	R _{θJA}	833	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55~+150	°C
Lead Temperature for Soldering Purposes(1/8" from case for 10s)	T _L	260	°C

P-channel MOSFET ELECTRICAL CHARACTERISTICS($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-20			V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}} = -20\text{V}, V_{\text{GS}} = 0\text{V}$			-1	μA
Gate-body leakage current	I_{GSS}	$V_{\text{GS}} = \pm 10\text{V}, V_{\text{DS}} = 0\text{V}$			± 20	μA
Gate threshold voltage ⁽²⁾	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-0.35	-0.60	-1.1	V
Drain-source on-resistance ⁽²⁾	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -4.5\text{V}, I_D = -1\text{A}$		450	580	$\text{m}\Omega$
		$V_{\text{GS}} = -2.5\text{V}, I_D = -0.8\text{A}$		650	840	
		$V_{\text{GS}} = -1.8\text{V}, I_D = -0.5\text{A}$		950		
Forward transconductance	g_{FS}	$V_{\text{DS}} = -10\text{V}, I_D = -0.54\text{A}$		1.2		S
Diode forward voltage ⁽³⁾	V_{DS}	$I_S = -0.5\text{A}, V_{\text{GS}} = 0\text{V}$			-1.2	V
DYNAMIC CHARACTERISTICS⁽⁴⁾						
Input Capacitance	C_{iss}	$V_{\text{DS}} = -16\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		113		pF
Output Capacitance	C_{oss}			15		
Reverse Transfer Capacitance	C_{rss}			9		
SWITCHING CHARACTERISTICS^(3,4)						
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = -10\text{V}, I_D = -200\text{mA}, V_{\text{GS}} = -4.5\text{V}, R_G = 10\Omega$		9		nS
Turn-on rise time	t_r			5.7		
Turn-off delay time	$t_{\text{d}(\text{off})}$			32.6		
Turn-off fall time	t_f			20.3		

N-channel MOSFET ELECTRICAL CHARACTERISTICS($T_a=25^\circ\text{C}$ unless otherwise noted)

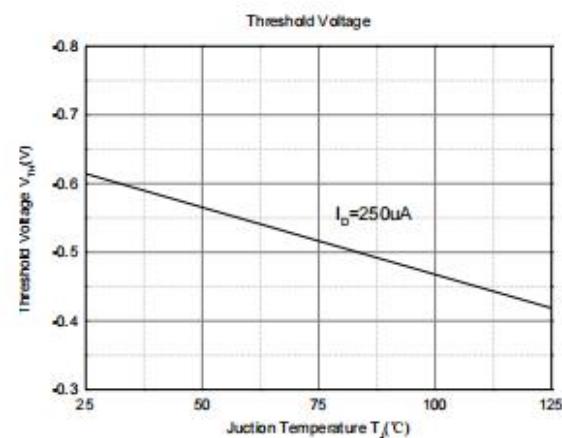
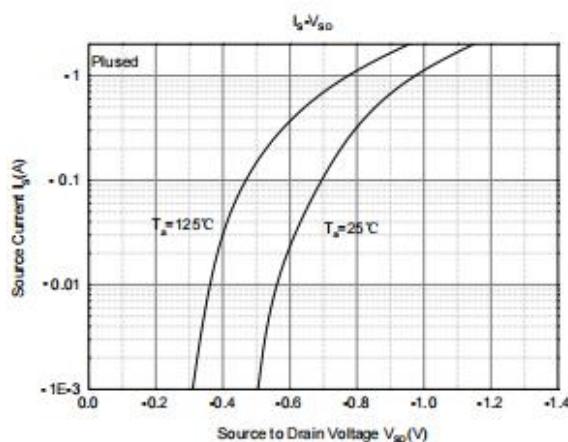
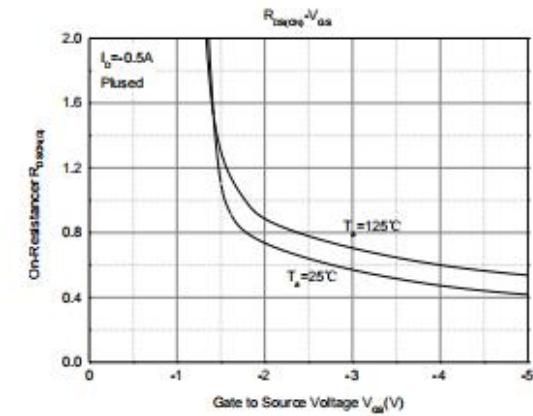
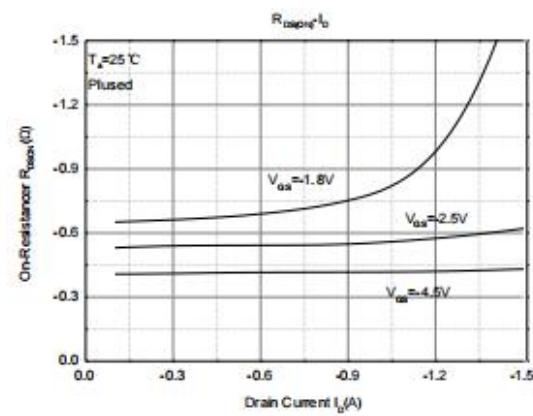
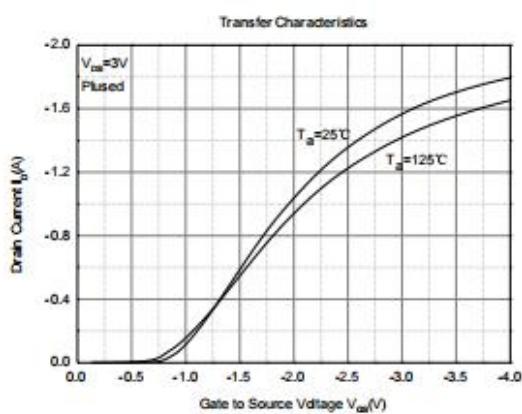
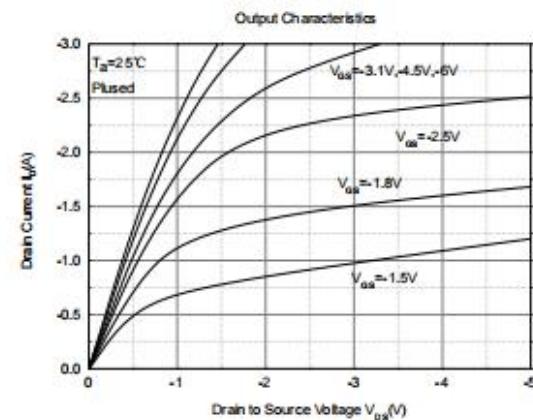
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 250\mu\text{A}$	20			V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate-body leakage current	I_{GSS}	$V_{\text{GS}} = \pm 10\text{V}, V_{\text{DS}} = 0\text{V}$			± 20	μA
Gate threshold voltage ⁽²⁾	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = 250\mu\text{A}$	0.35	0.75	1.1	V
Drain-source on-resistance ⁽²⁾	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 4.5\text{V}, I_{\text{D}} = 650\text{mA}$		190	260	$\text{m}\Omega$
		$V_{\text{GS}} = 2.5\text{V}, I_{\text{D}} = 550\text{mA}$		260	360	
		$V_{\text{GS}} = 1.8\text{V}, I_{\text{D}} = 450\text{mA}$		390	590	
Forward tranconductance	g_{FS}	$V_{\text{DS}} = 10\text{V}, I_{\text{D}} = 800\text{mA}$		1.6		S
Diode forward voltage ⁽³⁾	V_{DS}	$I_{\text{S}} = 0.15\text{A}, V_{\text{GS}} = 0\text{V}$			1.2	V
DYNAMIC CHARACTERISTICS⁽⁴⁾						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 16\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		79	120	pF
Output Capacitance	C_{oss}			13	20	
Reverse Transfer Capacitance	C_{rss}			9	15	
SWITCHING CHARACTERISTICS^(3,4)						
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = 10\text{V}, I_{\text{D}} = 500\text{mA}, V_{\text{GS}} = 4.5\text{V}, R_{\text{G}} = 10\Omega$		6.7		nS
Turn-on rise time	t_{r}			4.8		
Turn-off delay time	$t_{\text{d}(\text{off})}$			17.3		
Turn-off fall time	t_{f}			7.4		

Notes:

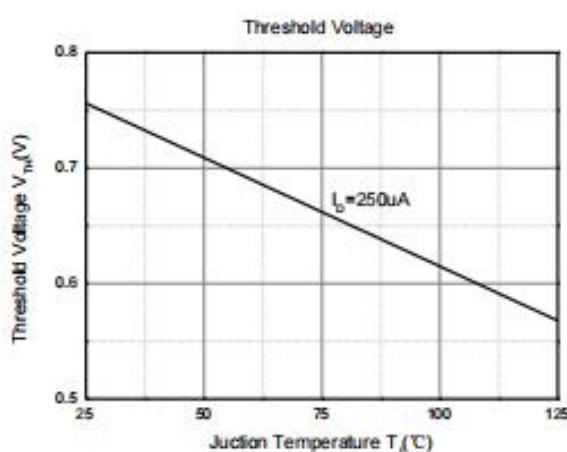
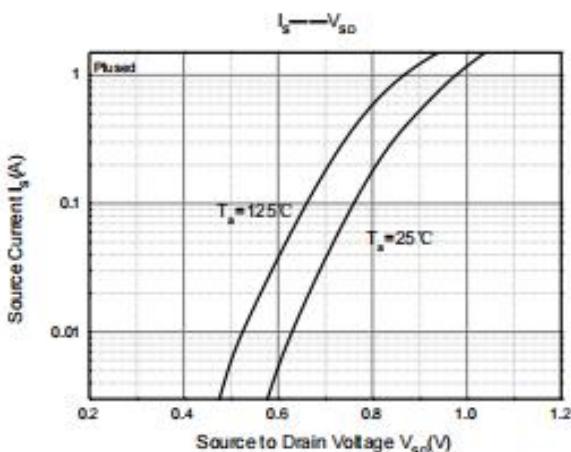
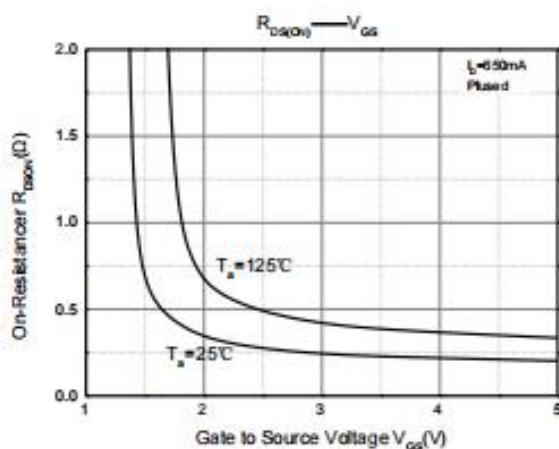
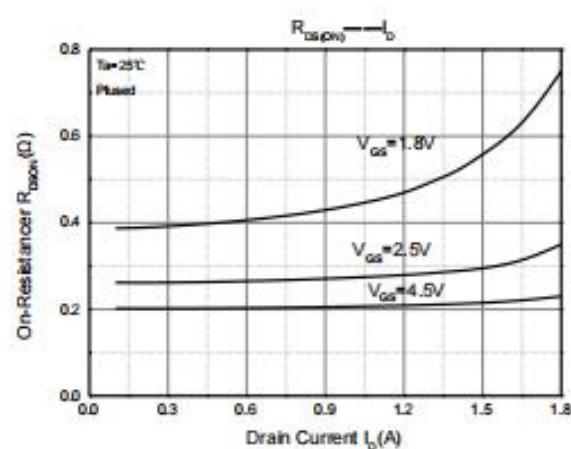
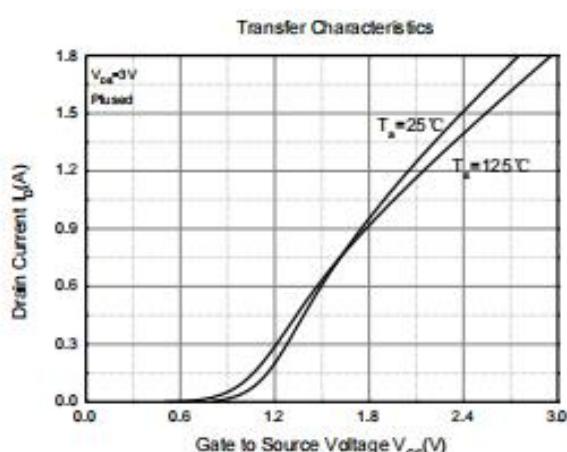
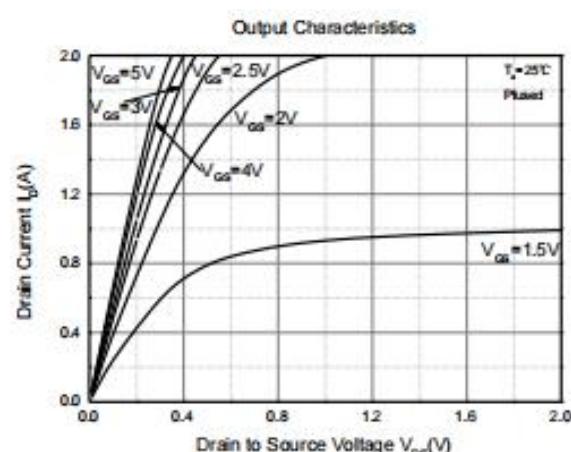
- 1.Surface mounted on FR4 board using the minimum recommended pad size.
- 2.Pulse Test : Pulse Width=300 μs , Duty Cycle=2%.
- 3.Switching characteristics are independent of operating junction temperatures.
- 4.Guaranteed by design, not subject to producing.

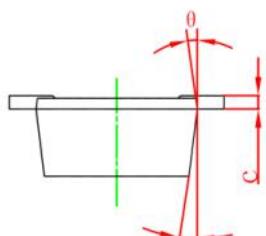
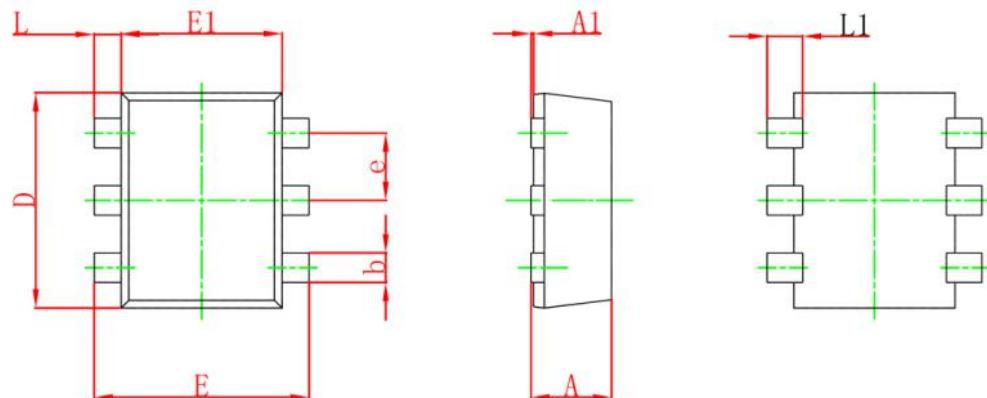
Typical Electrical and Thermal Characteristics

P-Channel MOS



N-Channel MOS

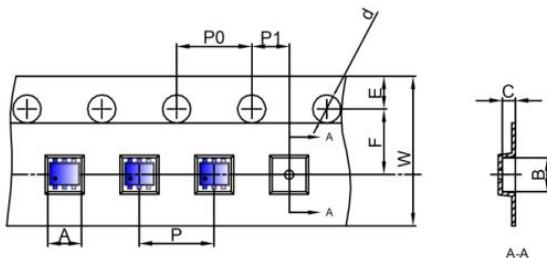




Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.525	0.600	0.021	0.024
A1	0.000	0.050	0.000	0.002
e	0.450	0.550	0.018	0.022
c	0.090	0.160	0.004	0.006
D	1.500	1.700	0.059	0.067
b	0.170	0.270	0.007	0.011
E1	1.100	1.300	0.043	0.051
E	1.500	1.700	0.059	0.067
L	0.100	0.300	0.004	0.012
L1	0.200	0.400	0.008	0.016
θ	7°REF.		7°REF.	

SOT-563 Tape and Reel

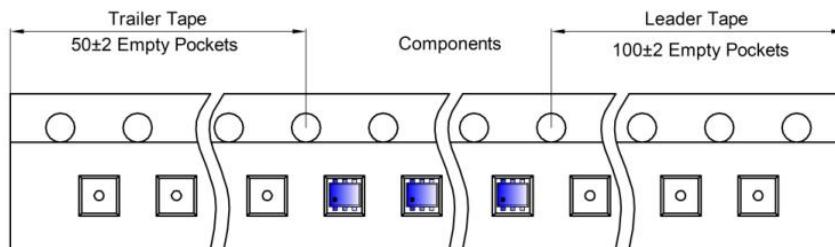
SOT-563 Embossed Carrier Tape



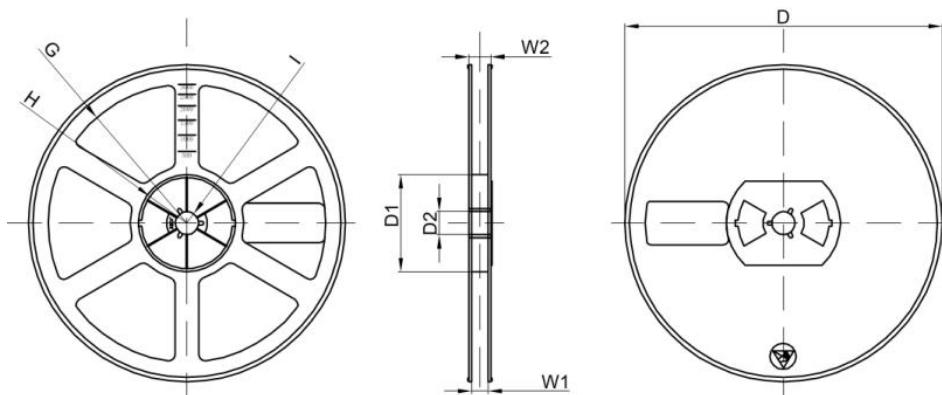
Dimensions are in millimeter

Pkg type	A	B	C	d	E	F	P0	P	P1	W
SOT-563	1.78	1.78	0.69	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00

SOT-563 Tape Leader and Trailer



SOT-563 Reel



Dimensions are in millimeter

Reel Option	D	D1	D2	G	H	I	W1	W2
7" Dia	Ø178.00	54.40	13.00	R78.00	R25.60	R6.50	9.50	12.30

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
3000 pcs	7 inch	30,000 pcs	203×203×195	120,000 pcs	438×438×220	